

Challenges in using nano-textured surfaces to reduce pressure drop through microchannels

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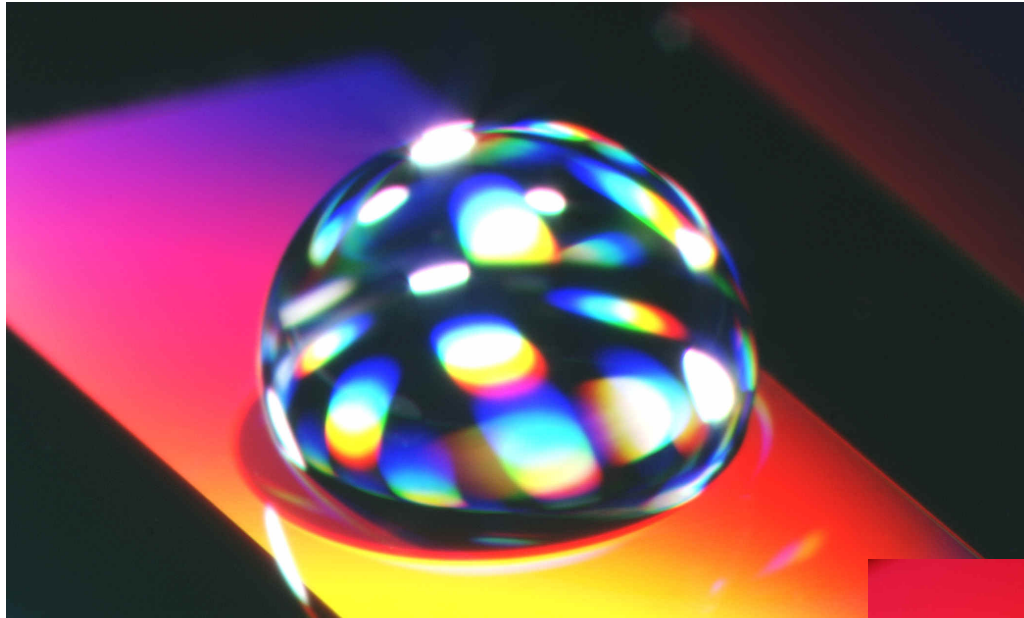
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Superhydrophobic Surfaces



Some possible applications

Lab-on-a-chip

Chemical and bio-sensors, micro reactors, genetic analysis, combinatorial chemistry

Electrical power cells

Novel reserve microbattery, fuel cell membranes

Microfluidics

Controllable “friction” channels , microfluidic mixers, pumps

Thermal management

On-chip hot spot mitigation, tunable thermal sinks

Drag reduction

Drag reduction, drag control, underwater steering and propulsion

Optics

Dynamic wavelength selective filters, tunable diffraction grating

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Thermal Management

Thermal management challenges in the electronics industry today.

- Integrated circuits (MPU's, GPU's, ASIC's, etc.)

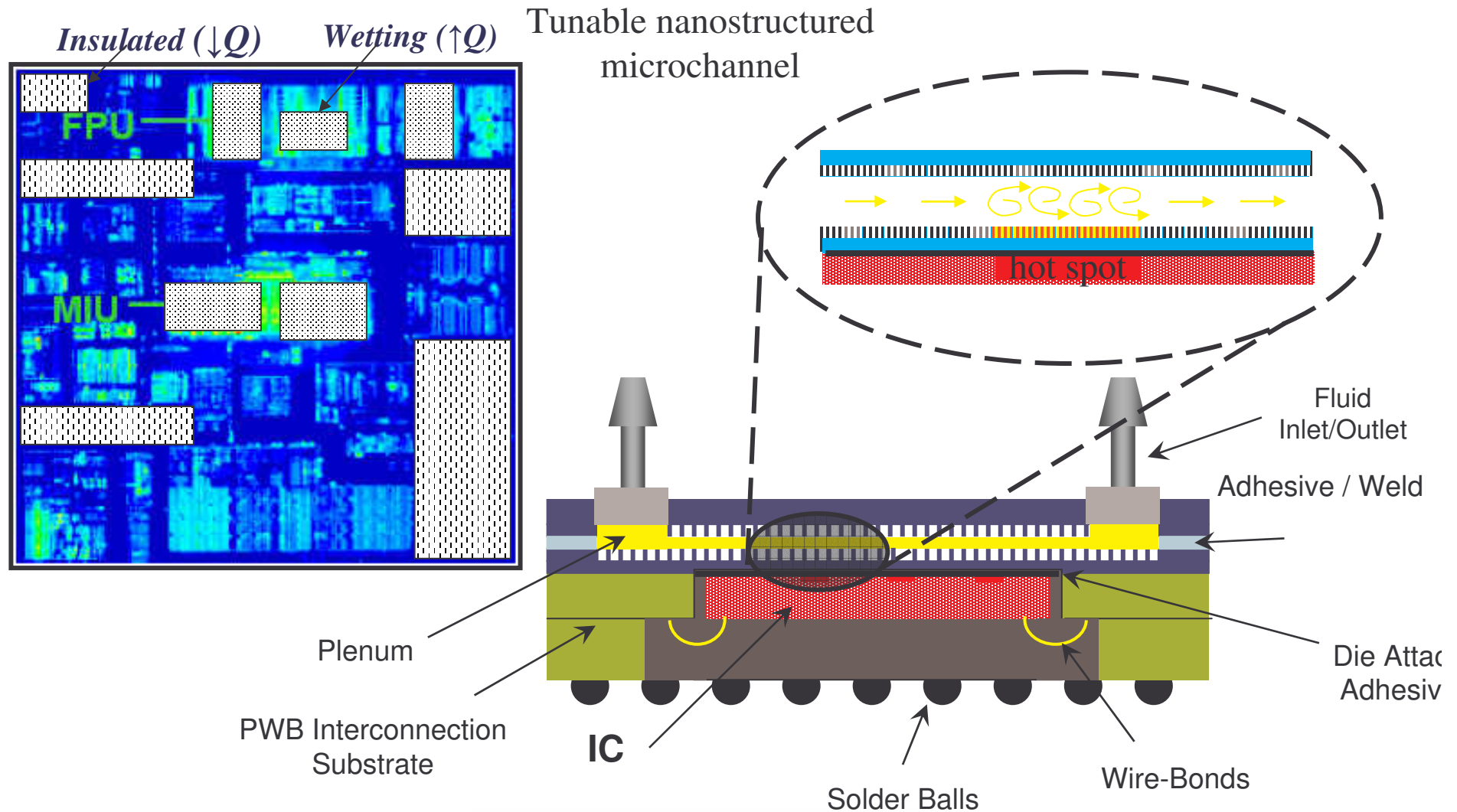
- Power levels are increasing to afford higher performance offsetting the trend of lower capacitances and voltages due to shrinking chip geometries.

$$P \propto fCV^2$$

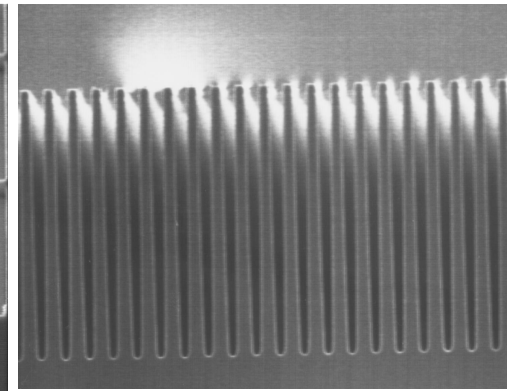
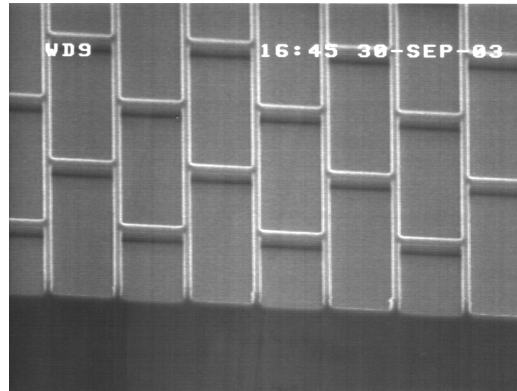
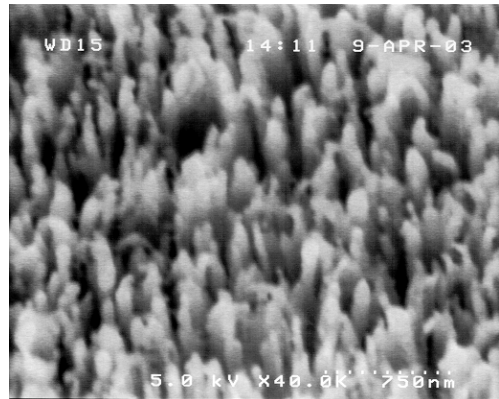
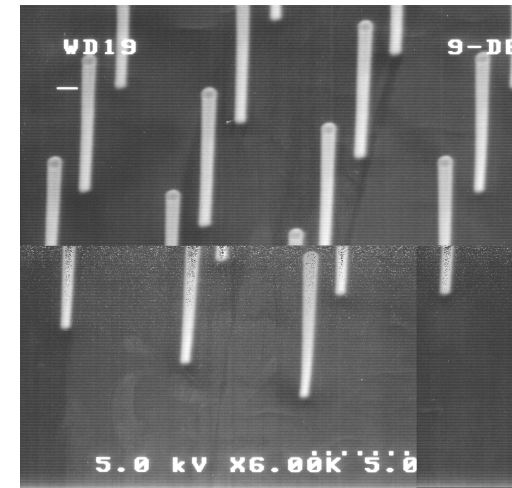
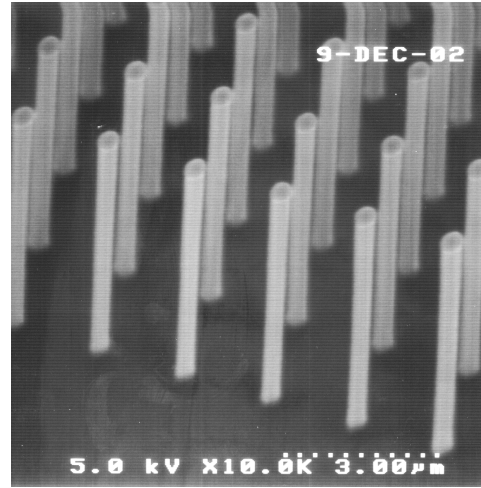
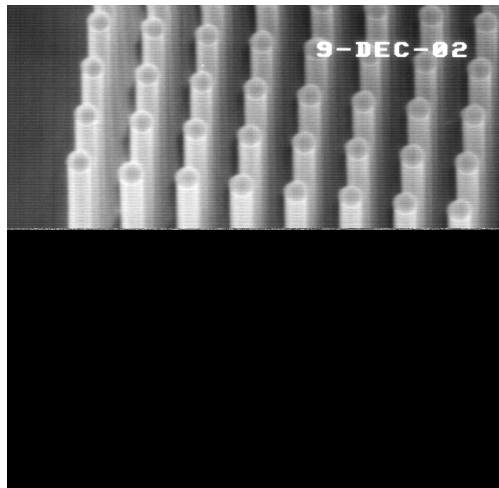
$f \rightarrow$ frequency
 $C \rightarrow$ effective switching capacitance
 $V \rightarrow$ supply voltage

- ITRS and iNEMI project heat fluxes of 100+ W/cm² in 10 years.
- Power is the #1 limitation beyond the 65 nm generation. (Nassif, IBM)
- Intel shifts its processor design strategy after hitting the thermal wall. (NY Times, 2004)
- On-die power distribution, e.g. “hot spots”, are a major concern.
 - Local heat fluxes >300 W/cm² are being realized.
 - Temperature gradients of 30°C on 22x22 mm silicon devices have been observed (Deeney, HP). This is a major issue with regards to chip operability and reliability.
- Cooling solutions must be capable of dealing not only with static power dissipation, but also large dynamic variations.

Thermal Management

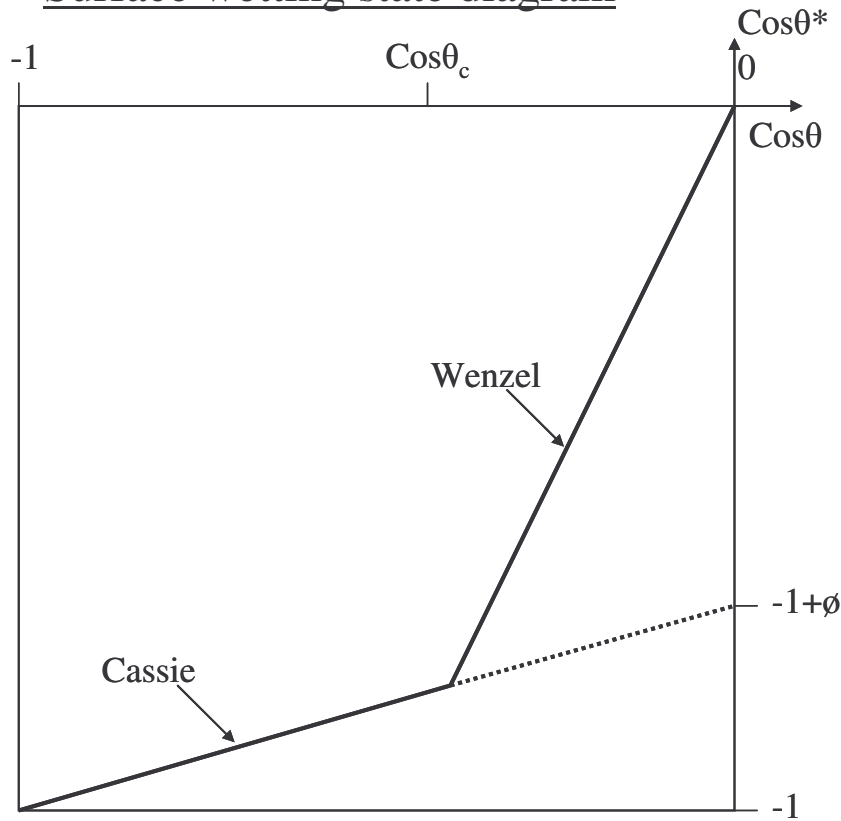


Superhydrophobic Surfaces



Superhydrophobic Surfaces

Surface wetting state diagram



Lafuma & Quéré (2003)

Cassie regime of wetting

$$\cos \theta^* = -1 + \phi(1 + \cos \theta)$$

$\theta^* \rightarrow$ apparent contact angle

$\phi \rightarrow$ ratio of contact area to projected area

$\theta \rightarrow$ contact angle

Cassie & Baxter. (1944)

Wenzel regime of wetting

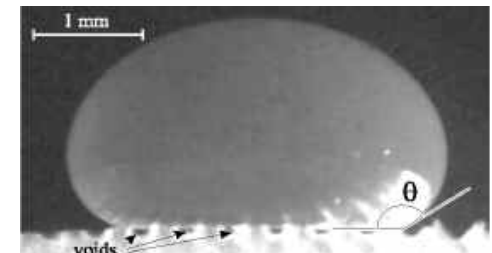
$$\cos \theta^* = r \cos \theta$$

$\theta^* \rightarrow$ apparent contact angle

$r \rightarrow$ ratio of true area to projected area

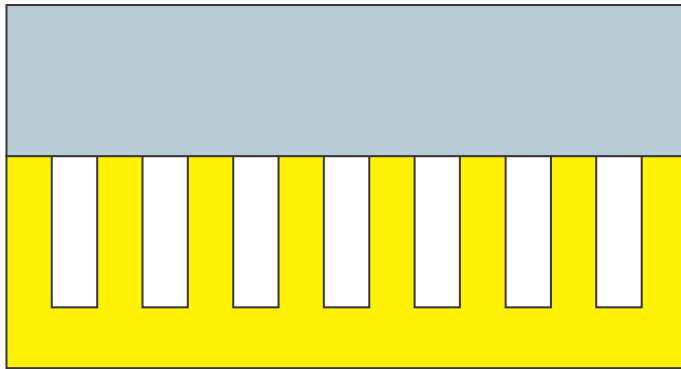
$\theta \rightarrow$ contact angle

Gogte *et. al.* (2005)

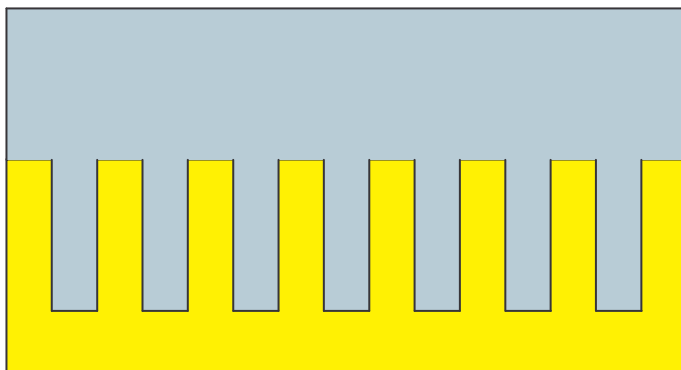


Superhydrophobic Surfaces

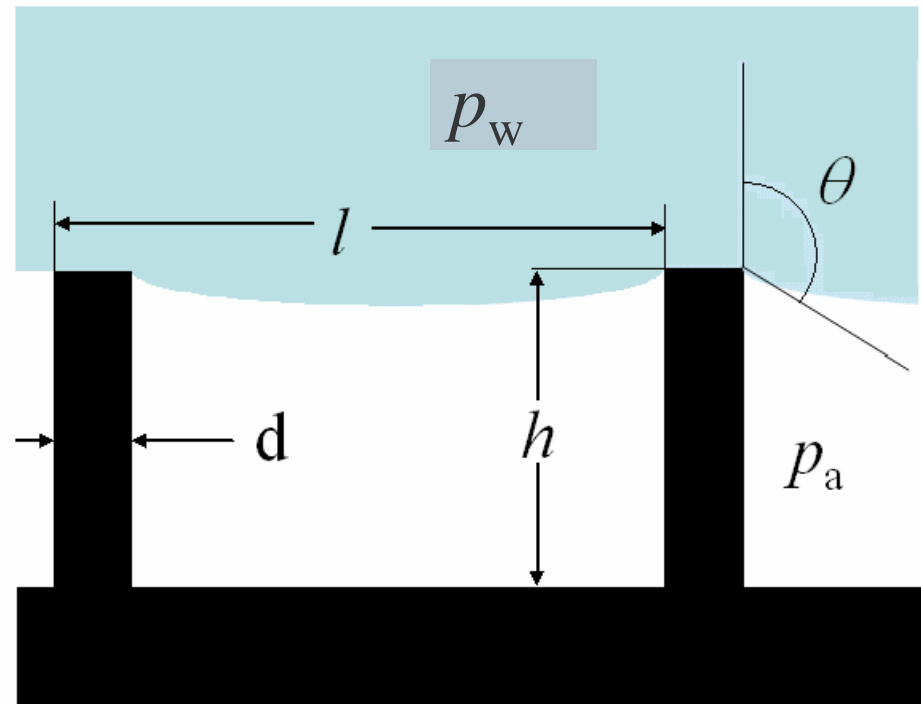
Cassie regime of wetting



Wenzel regime of wetting

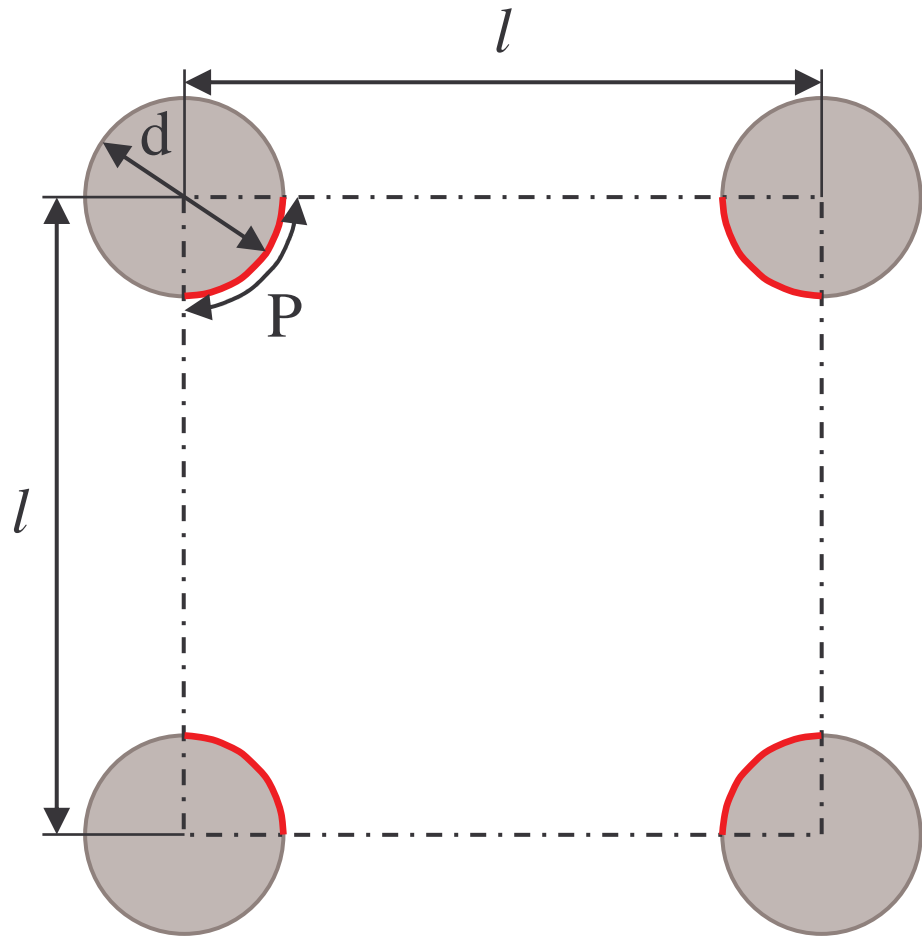


Irreversible wetting transition



$$\Delta p = p_w + p_a$$

Interfacial Pressure Stability



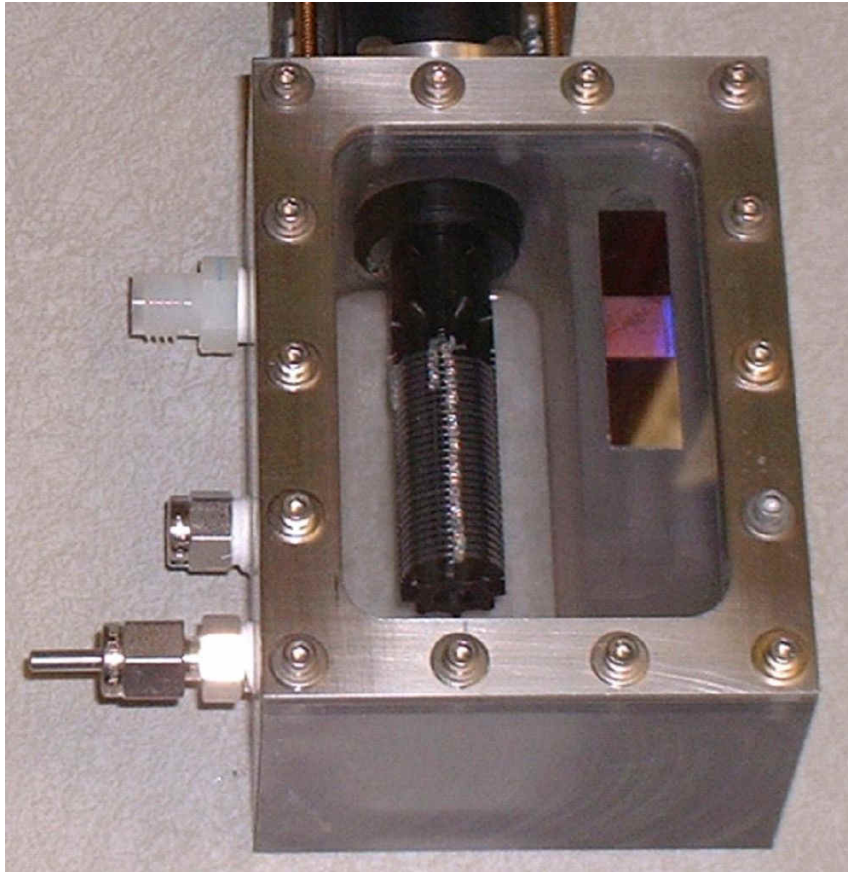
$$A\Delta p = -P\gamma \cos \theta$$

$$\left(l^2 - \frac{\pi d^2}{4} \right) \Delta p = -\pi d \gamma \cos \theta$$

$$\Delta p = -\frac{\pi d \gamma \cos \theta}{\left(l^2 - \frac{\pi d^2}{4} \right)}$$



Interfacial Pressure Stability



Roughness geometry

$$d = 200 \text{ nm}$$

$$l = 2 \text{ } \mu\text{m}$$

$$h = 7.5 \text{ } \mu\text{m}$$

Interfacial chemistry

$$\theta = 110^\circ \text{ (PTFE)}$$

$$\gamma_{LV} = 72.75 \text{ mN/m (Water)}$$

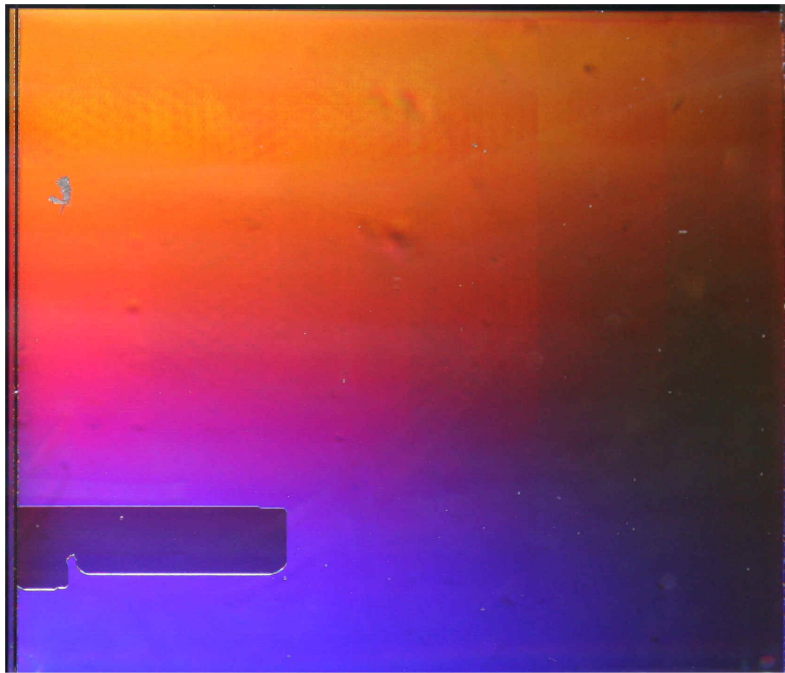
Critical pressure differential

$$\Delta p_c \approx 4 \text{ kPa}$$



Interfacial Pressure Stability

$$p_w = 9.2 \text{ kPa} \quad p_w / \Delta p_c = 2.3$$



seconds after onset of wetting



168 seconds later

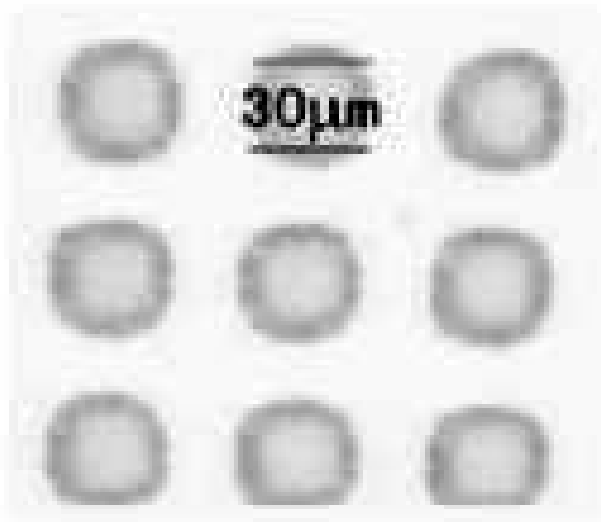
Air layer is a trapped volume, thus progression of wetting likely dictated by the diffusion of air into water.



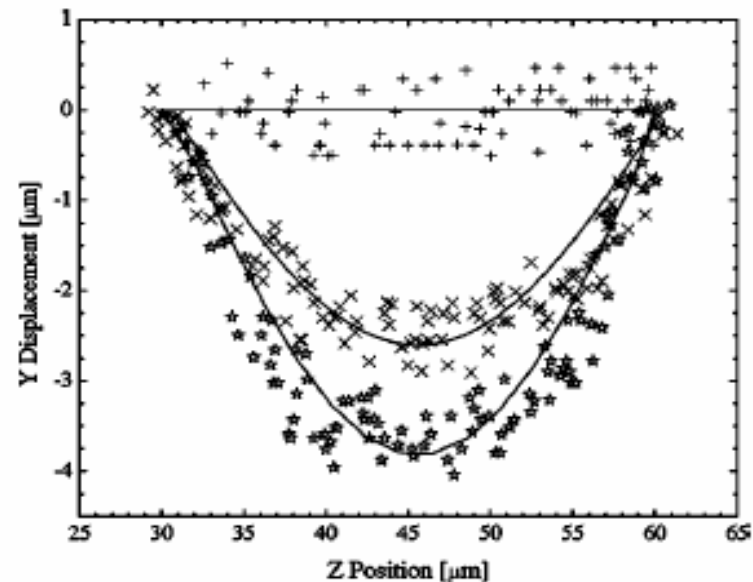
Superhydrophobic Microchannel Experiment

Ou *et al.* (2004), “Laminar drag reduction in microchannels using ultrahydrophobic surfaces.”

- Achieved drag reduction of up to 40% on structured superhydrophobic surfaces
- Identified & measured the deflection of the surface tension interface using confocal microscopy



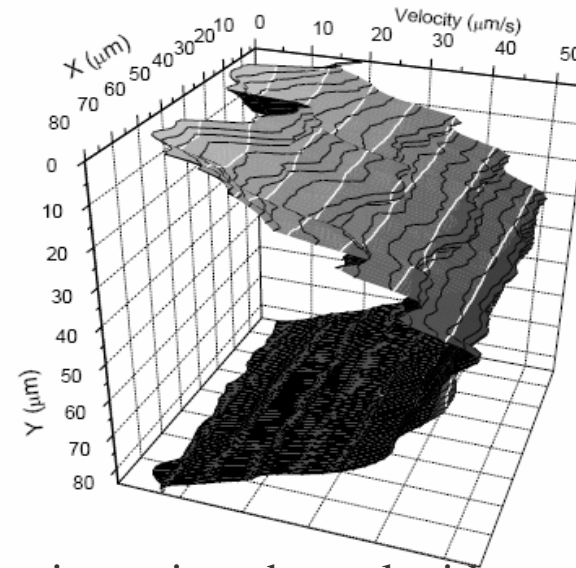
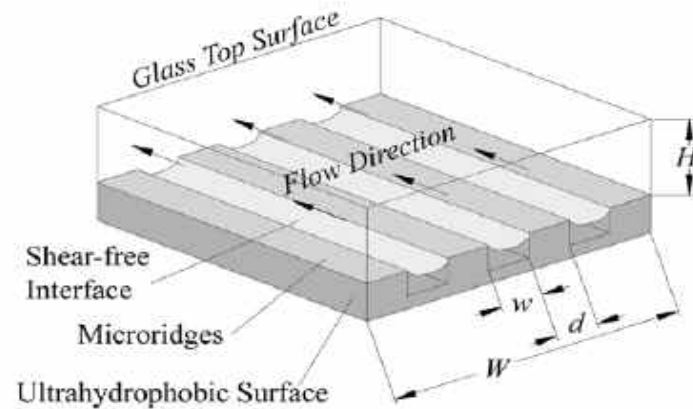
Plan view image of post structures studied by Ou and colleagues.



Air/water interface deflection under pressure as measured by confocal microscopy.

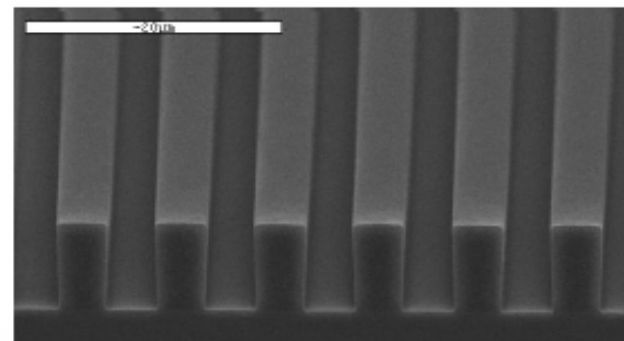
Superhydrophobic Microchannel Experiment

Ou & Rothstein (2005), “Drag Reduction and μ -PIV Measurements of the Flow Past Ultrahydrophobic Surfaces”



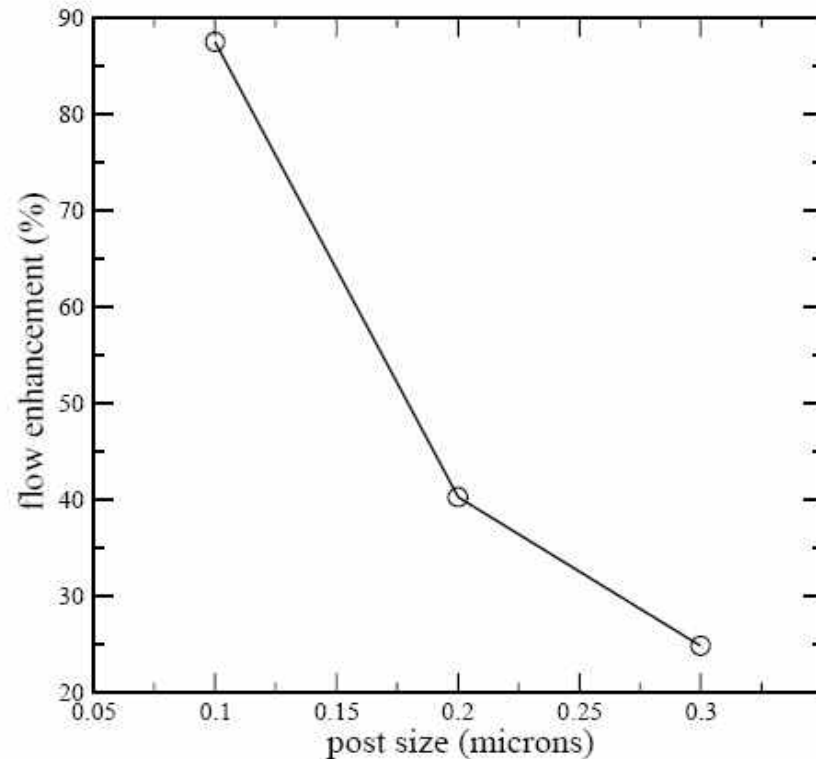
Woolford *et. al.* (2005), “Laminar fully-developed flow in a microchannel with patterned ultrahydrophobic walls.”

- Observed drag reduction of up to 30%

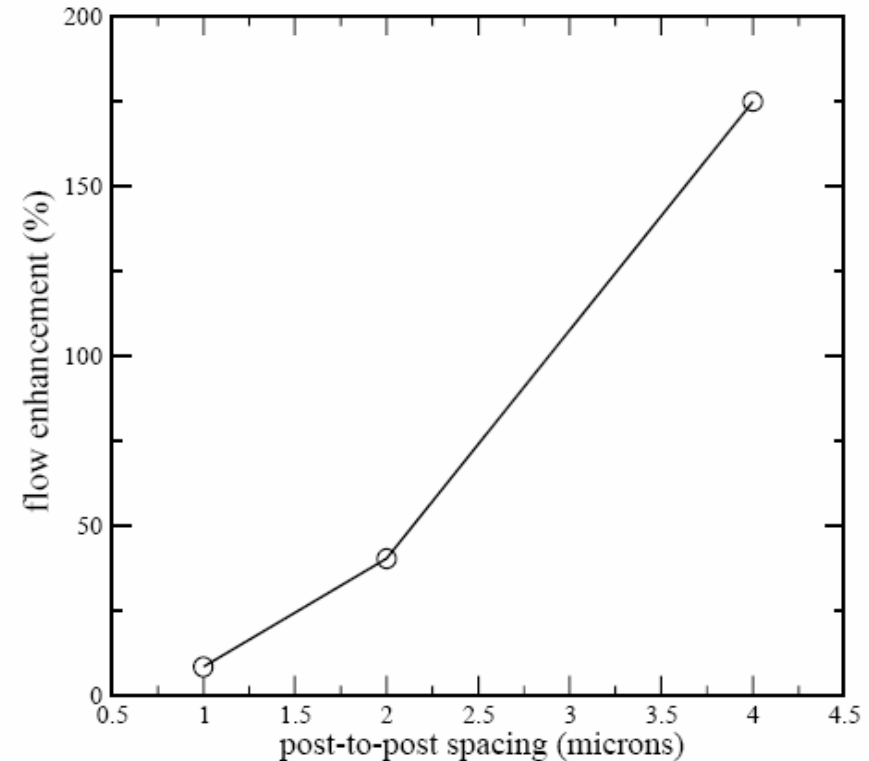


Superhydrophobic Microchannel Simulation

Salamon et. al., 2005. “Numerical Simulation of Fluid Flow in Microchannels with Superhydrophobic Walls”



Flow enhancement as a function of post spacing. $d=200$ nm

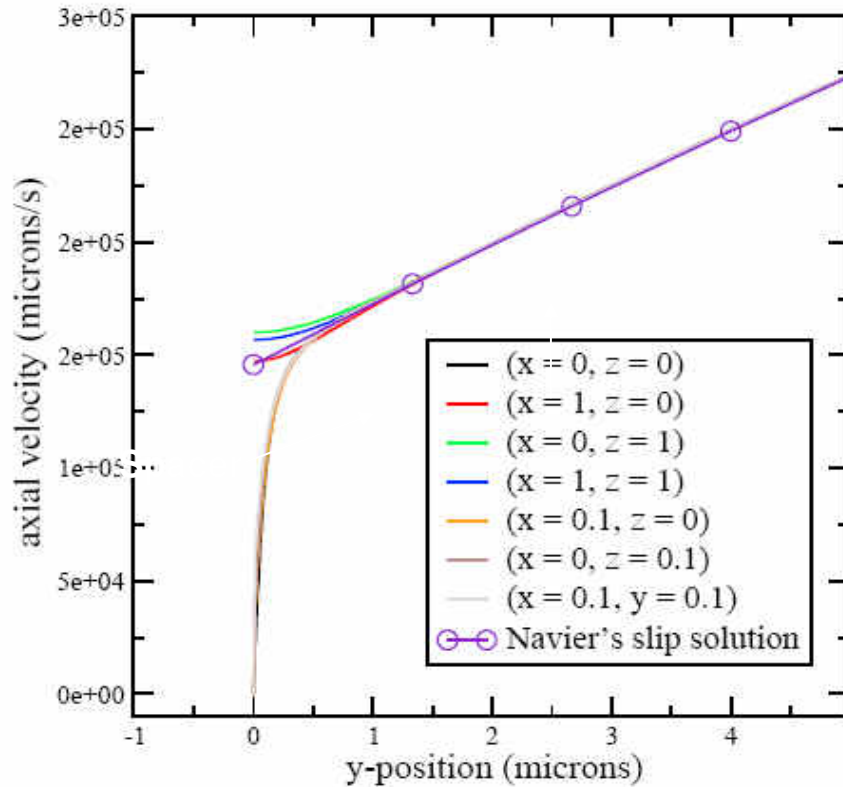


Flow enhancement as a function of post size. $l=2$ μm

Simulation predicts drag reduction of 40% for the superhydrophobic surfaces currently being investigated.

Superhydrophobic Microchannel

Application of the Navier slip hypothesis. $\longrightarrow v_x|_{y=0} = b \frac{dv_x}{dy} \Big|_{y=0}$



Two superhydrophobic walls

$$v_x(y) = \left(-\frac{\Delta p}{\Delta L} \right) \left(\frac{H^2}{2\mu} \right) \left(\frac{b}{H} + \frac{y}{H} - \frac{y^2}{H^2} \right)$$

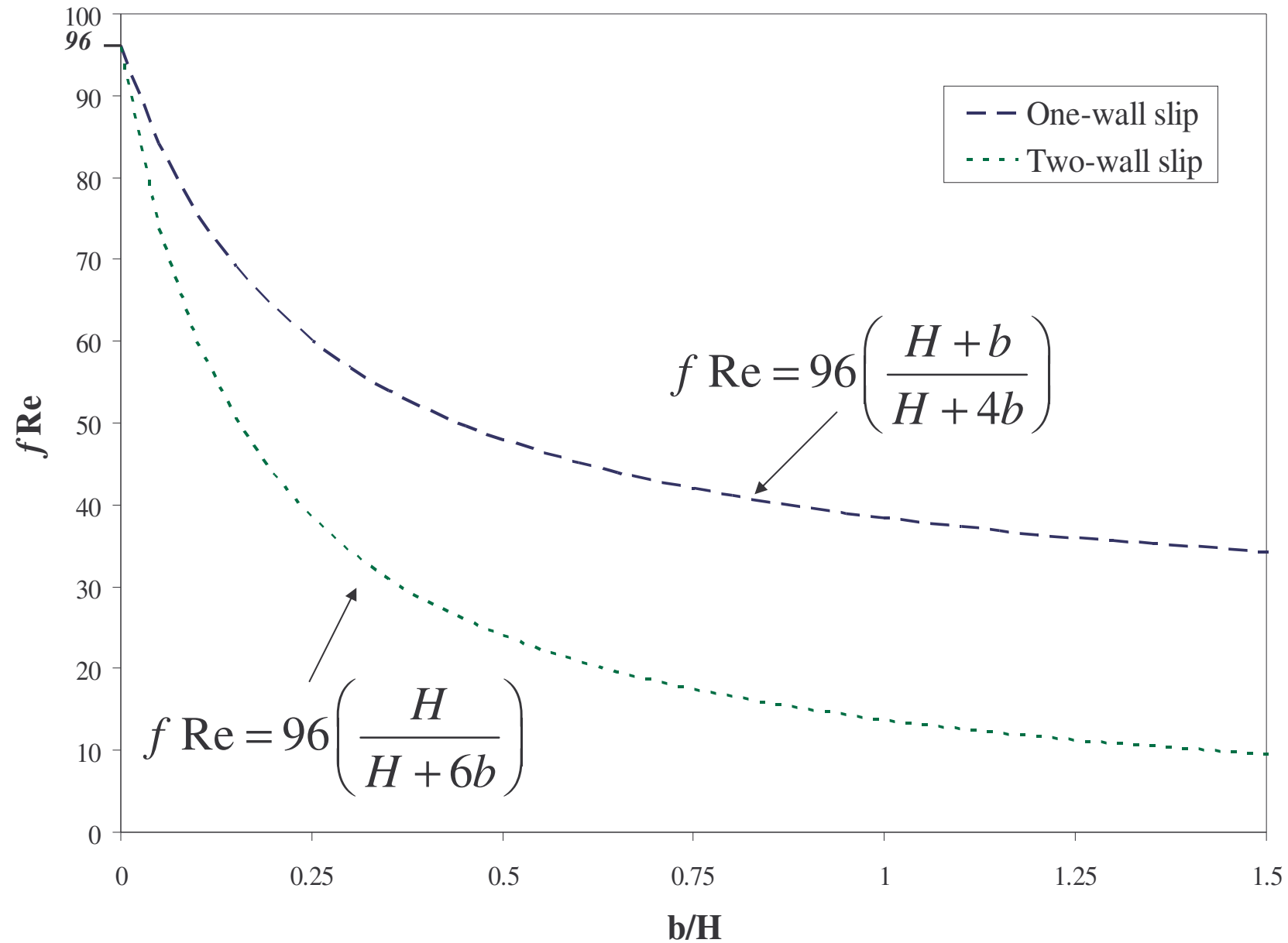
$$Q = \left(-\frac{\Delta p}{\Delta L} \right) \left(\frac{H^3}{2\mu} \right) \left(\frac{b}{H} + \frac{1}{6} \right)$$

One superhydrophobic wall

$$v_x(y) = \left(-\frac{\Delta p}{\Delta L} \right) \left(\frac{1}{\mu} \right) \left(-\frac{y^2}{2} - \left\{ \frac{bH + H^2/2}{H+b} \right\} y \right)$$

$$Q = \left(-\frac{\Delta p}{\Delta L} \right) \left(\frac{H^3}{12\mu} \right) \left(\frac{H+4b}{H+b} \right)$$

Superhydrophobic Microchannel



Superhydrophobic Microchannel

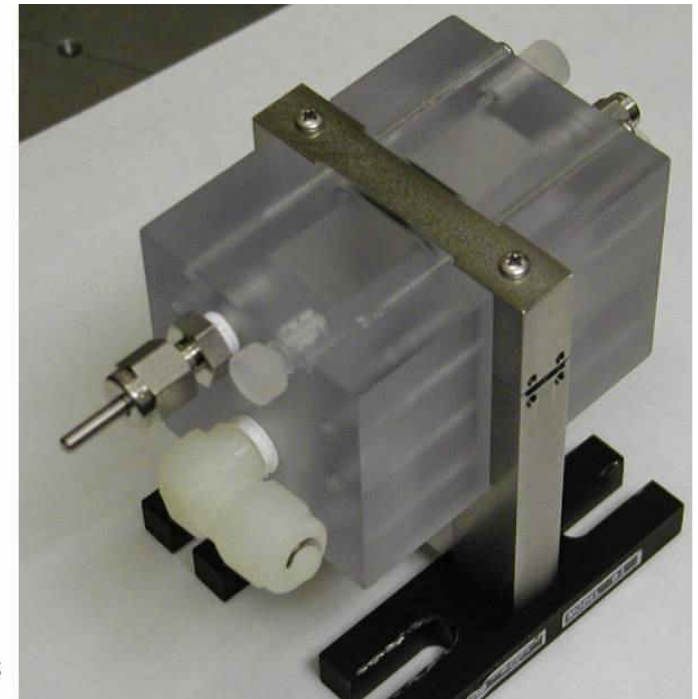
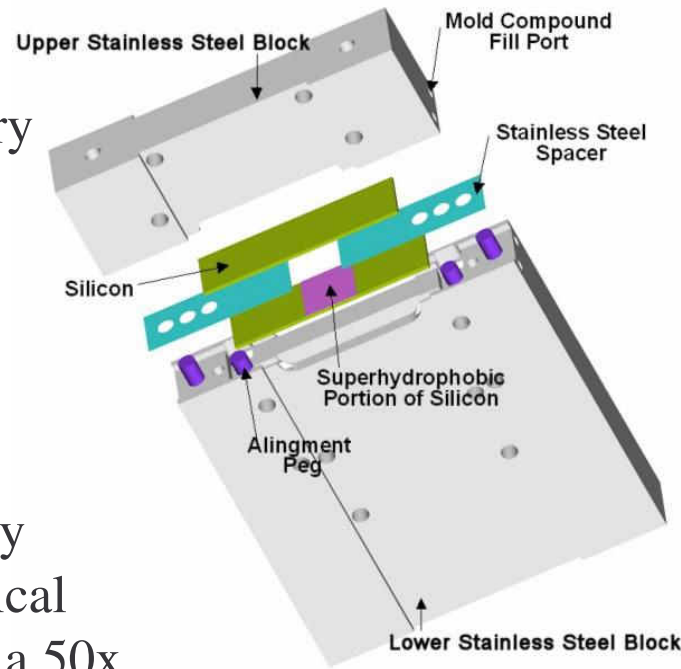
Parallel-plane geometry

Height = $86\text{ }\mu\text{m}$

Width = 9.93 mm

Length = 9.91 mm

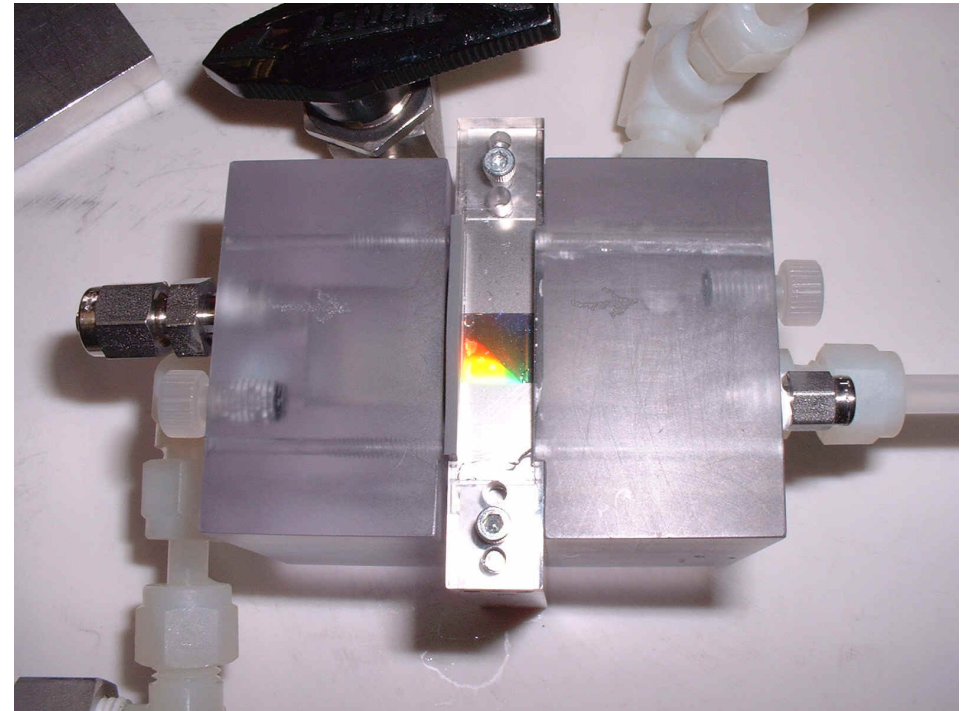
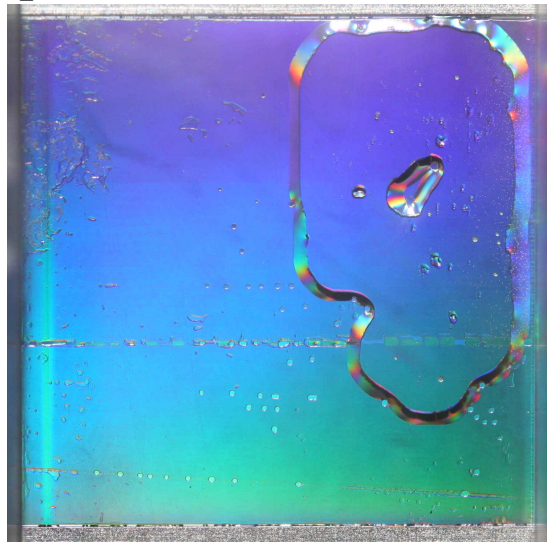
Dimensions accurately measured using a optical positioning stage and a 50x objective



Superhydrophobic Microchannel

Polycarbonate “top plate” designed to allow optical access in order to:

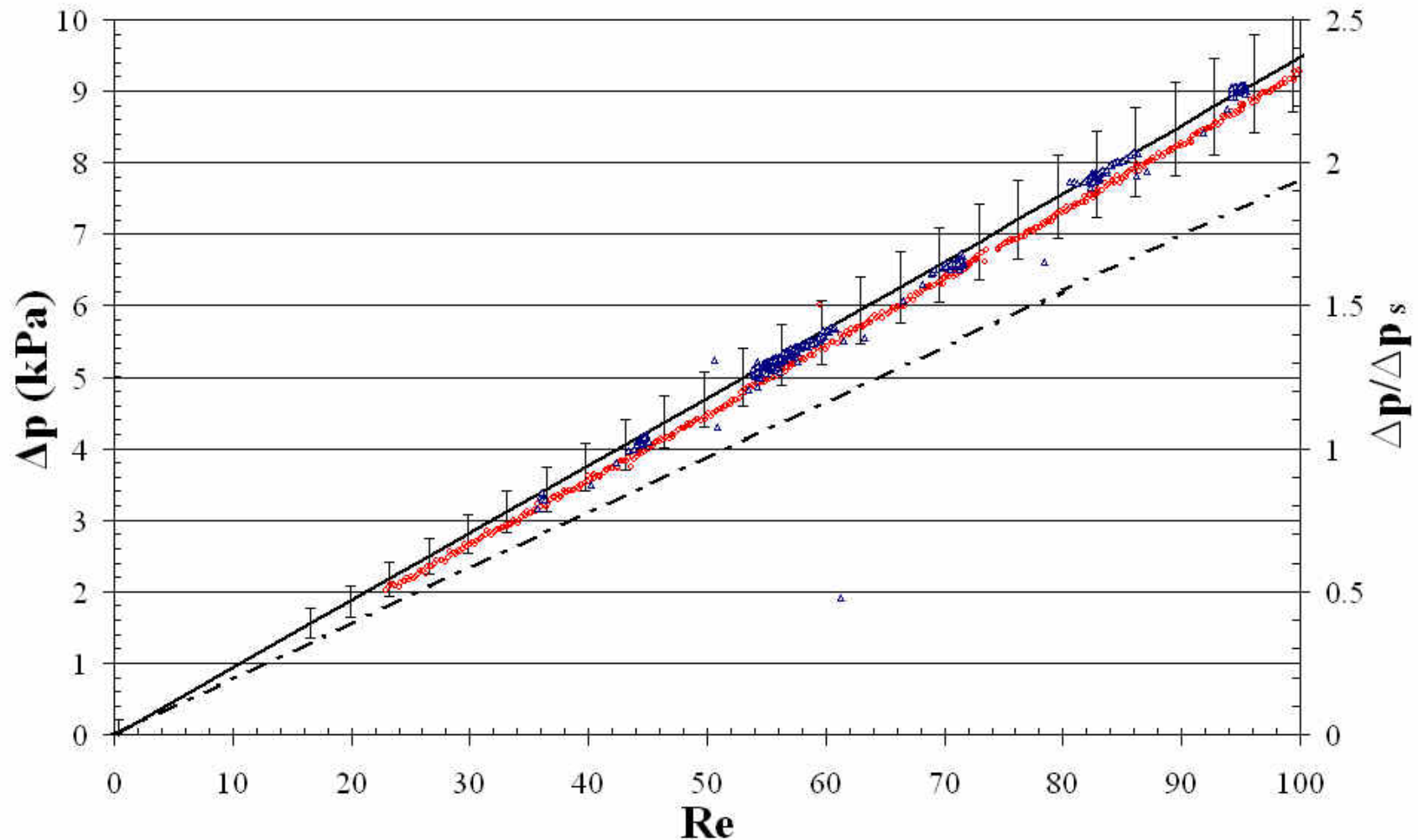
- Confirm experimental procedure
- Observe bubble formation and behavior
- Observe the wetting behavior of the nanograss surface under flow conditions
- Provide a possible means for future optical measurements



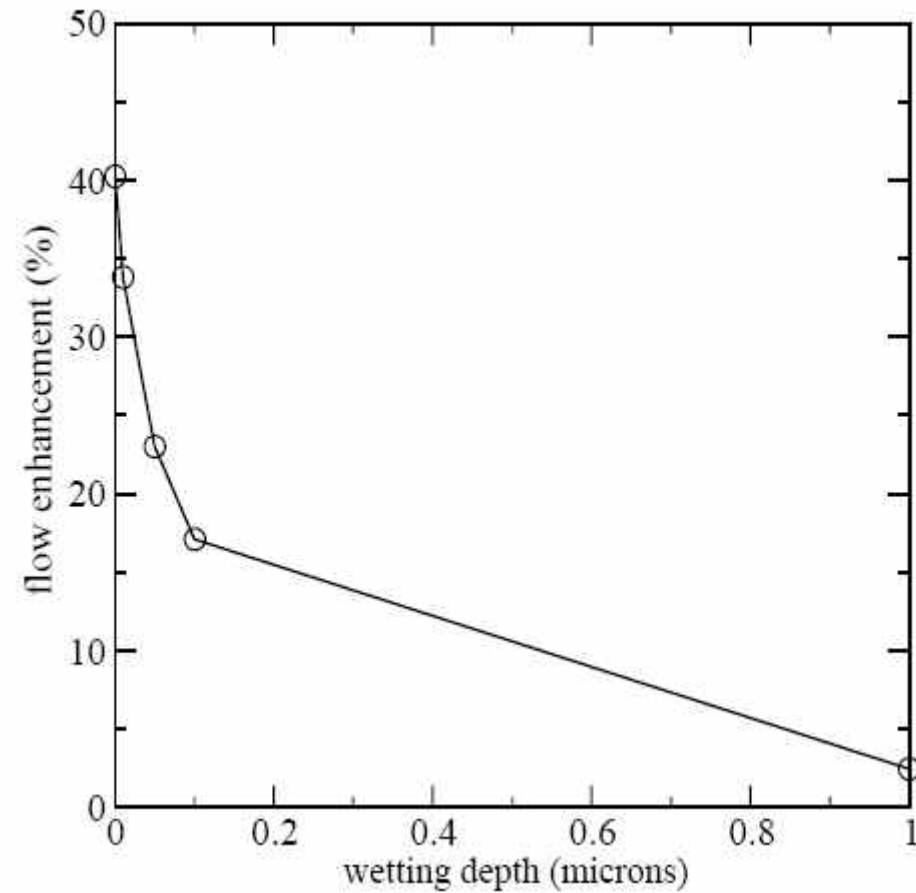
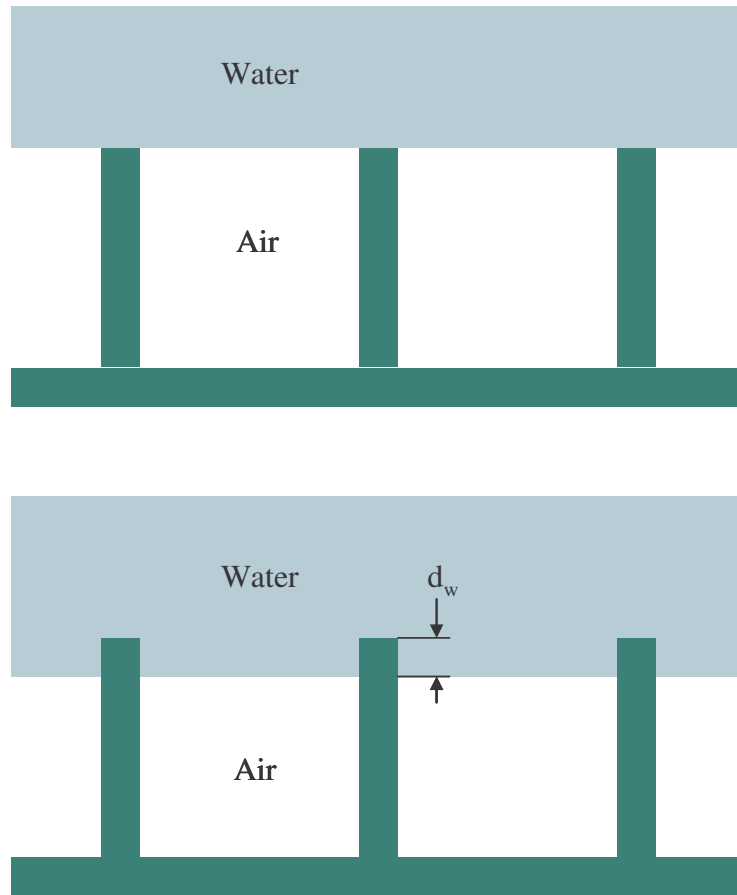
Assembled test section w/ optical access

Image of an air bubble on the nanograss surface under static conditions.

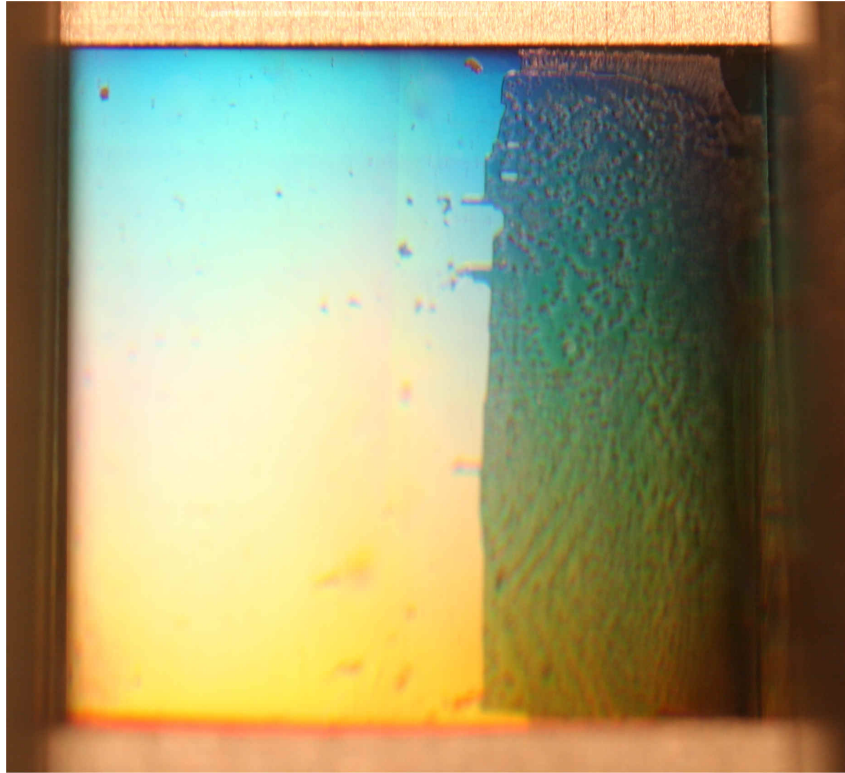
Superhydrophobic Microchannel



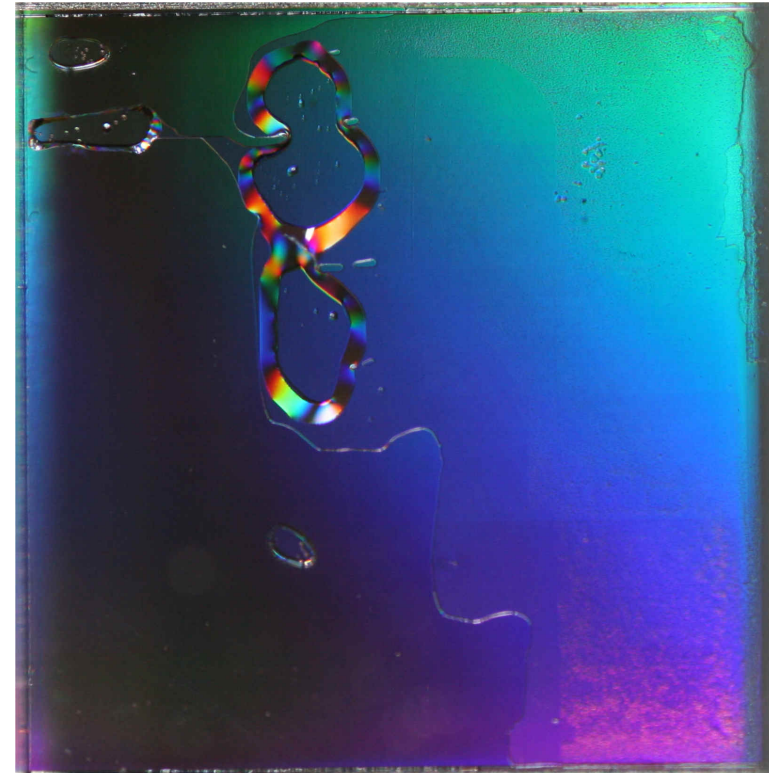
Superhydrophobic Microchannel



Dynamic Wetting



$Re = 444$; $dp=20.7$ kPa;
 $dp/dpc=5.175$



Bubble formed in channel, occluding flow

Two Wall Velocity Profile Solution

PROBLEM:

- Flow of Water between 2 Superhydrophobic walls. No slip BC at top ($y=H$) and bottom ($y=0$). Water layer sits between 2 layers of Gas trapped in a nanograss coating
- Velocity and shear matched at liquid - air interfaces
- The pressure driven movement of the water induces recirculating flow in the gas layers

3 Governing Momentum Equations: $\left. \frac{dP}{dx} \right|_{L,G1,G2} = \mu_{L,G1,G2} \frac{d^2 u_{L,G1,G2}}{dy^2}$

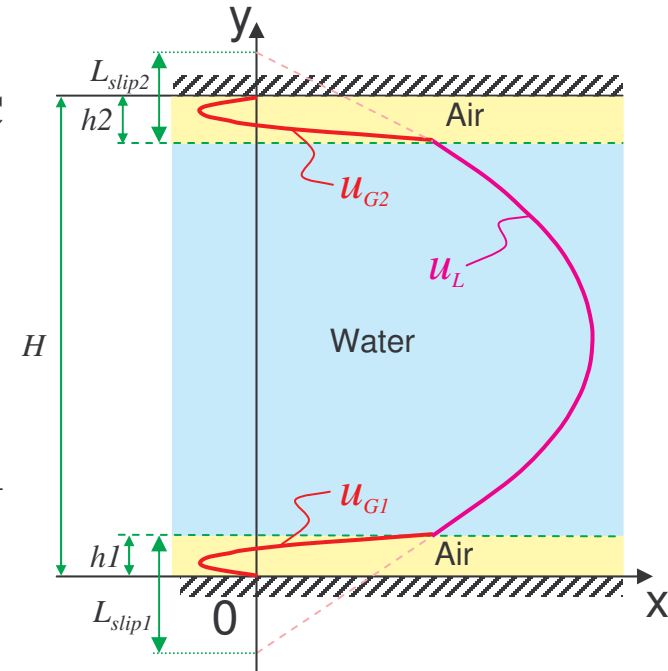
Nomenclature:

A, B	Integration Constants
H	Total Height of Flow Area (m)
$L_{slip1,2}$	Slip Lengths (m)
P	Pressure (Pa)
$h1, h2$	Height of Gas Layers (m)
$u_{L,1,2}$	Flow Velocity (m/s)
$\mu_{L,1,2}$	Viscosity (Pas)

Subscripts:

$G1, G2$	Property of Gas (Air) Layers
L	Property of Liquid Layer

Note: $\left. \frac{dP}{dx} \right|_L$ prescribed, $\left. \frac{dP}{dx} \right|_{G1}$ and $\left. \frac{dP}{dx} \right|_{G2}$ are unknown



Two Wall Velocity Profile Solution

Integrate each of the three Momentum Equations Twice:

$$u_{L,G1,G2} = \frac{dP_{L,G1,G2}}{dx} \frac{y^2}{2\mu_{L,G1,G2}} - \frac{A_{L,G1,G2}y}{\mu_{L,G1,G2}} - \frac{B_{L,G1,G2}}{\mu_{L,G1,G2}}$$

Boundary Conditions:

1. @y=0, $u_{G1}=0$
2. @y=H, $u_{G2}=0$
3. @y=h1, $u_{G1}=u_L$
4. @y=h1, $\mu_{G1} \frac{du_{G1}}{dy} = \mu_L \frac{du_L}{dy}$
5. @y=H-h2, $u_{G2}=u_L$
6. @y=H-h2, $\mu_{G2} \frac{du_{G2}}{dy} = \mu_L \frac{du_L}{dy}$
7. $\int_0^{h1} u_{G1} dy = 0$
8. $\int_{H-h2}^H u_{G2} dy = 0$

Simultaneous Equations:

Solve for: $A_L, A_{G1}, A_{G2}, B_L, B_{G1}, B_{G2}, \frac{dP_{G1}}{dz}, \frac{dP_{G2}}{dz}$

$$1. 0 = \frac{-B_{G1}}{\mu_{G1}}$$

$$2. 0 = \frac{dP_{G1}}{dx} \frac{H^2}{2\mu_{G2}} - \frac{A_{G2}H}{\mu_{G2}} - \frac{B_{G2}}{\mu_{G2}}$$

$$3. \frac{dP_{G1}}{dx} \frac{h1^2}{2\mu_{G1}} - \frac{A_{G1}h1}{\mu_{G1}} - \frac{B_{G1}}{\mu_{G1}} = \frac{dP_L}{dz} \frac{h1^2}{2\mu_L} - \frac{A_Lh1}{\mu_L} - \frac{B_L}{\mu_L}$$

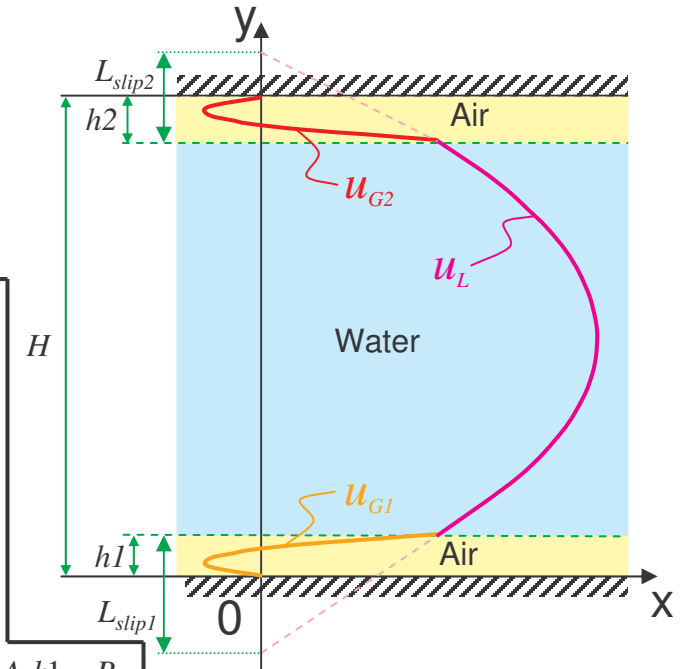
$$4. \mu_{G1} \left(\frac{dP_{G1}}{dx} \frac{h1}{\mu_{G1}} - \frac{A_{G1}}{\mu_{G1}} \right) = \mu_L \left(\frac{dP_L}{dx} \frac{h1}{\mu_L} - \frac{A_L}{\mu_L} \right)$$

$$5. \frac{dP_{G2}}{dx} \frac{(H-h2)^2}{2\mu_G} - \frac{A_G(H-h2)}{\mu_G} - \frac{B_G}{\mu_G} = \frac{dP_L}{dx} \frac{(H-h2)^2}{2\mu_L} - \frac{A_L(H-h2)}{\mu_L} - \frac{B_L}{\mu_L}$$

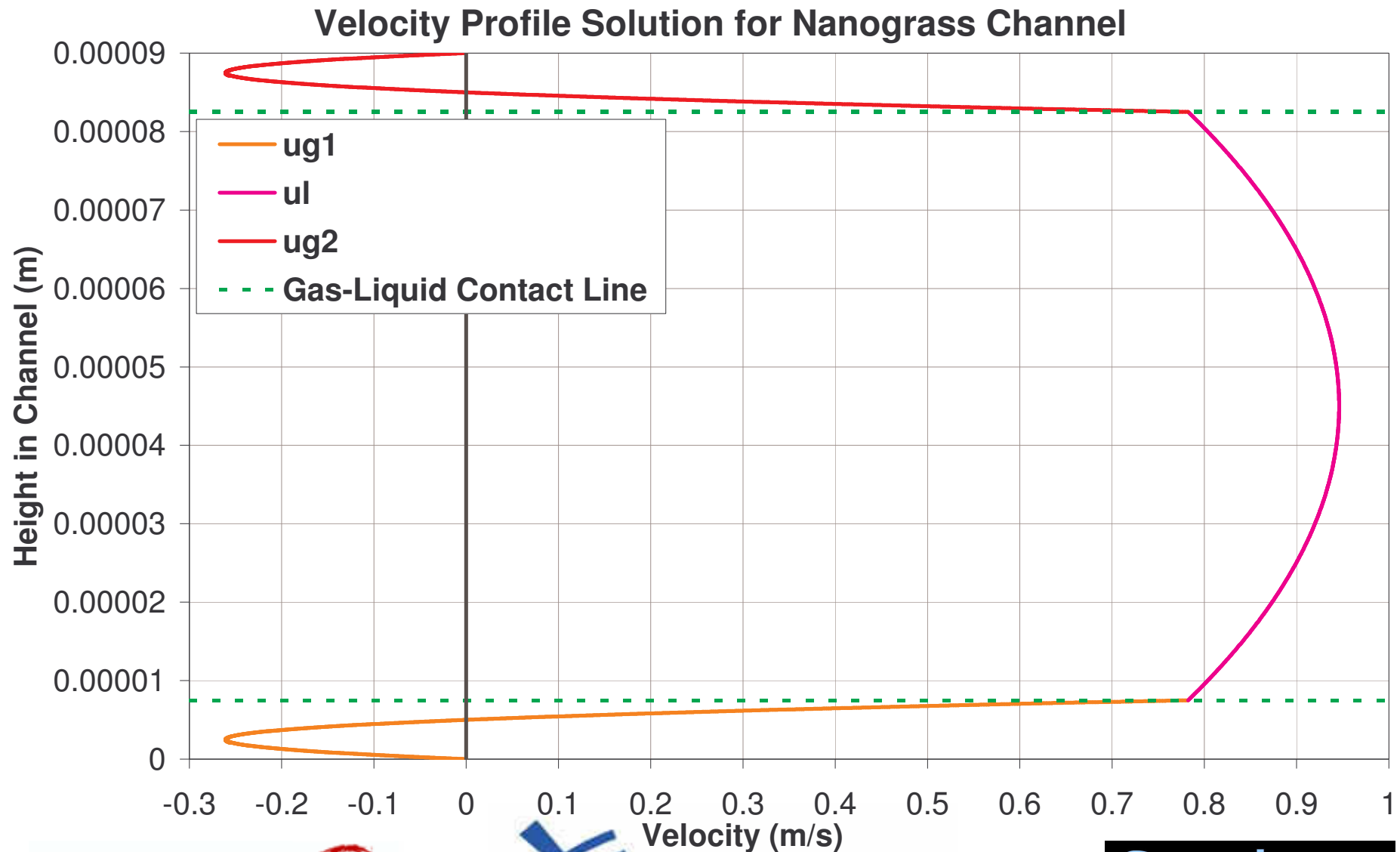
$$6. \mu_{G2} \left(\frac{dP_{G2}}{dx} \frac{(H-h2)}{\mu_{G2}} - \frac{A_{G2}}{\mu_{G2}} \right) = \mu_L \left(\frac{dP_L}{dx} \frac{(H-h2)}{\mu_L} - \frac{A_L}{\mu_L} \right)$$

$$7. \frac{dP_{G1}}{dx} \frac{h1^3}{6\mu_{G1}} - \frac{A_{G1}h1^2}{2\mu_{G1}} - \frac{B_{G1}h1}{\mu_{G1}} = 0$$

$$8. \frac{dP_{G2}}{dz} \frac{(H-h2)^3}{6\mu_{G2}} - \frac{A_{G2}(H-h2)^2}{2\mu_{G2}} - \frac{B_{G2}(H-h2)}{\mu_{G2}} = 0$$



Two Wall Velocity Profile Solution



Two Wall Temperature Profile Solution

PROBLEM:

- A Constant Heat Flux is Applied to the $y=0$ surface
- The $y=H$ surface is assumed adiabatic
- Where the air and water layers meet their temperatures are equal
- The heat that leaves one layer equals the heat entering the next layer

Energy Equation:
$$u \frac{\partial T}{\partial x} + v \frac{\partial T}{\partial y} = \alpha \frac{\partial^2 T}{\partial y^2}$$

Since $v=0$, Reduces to:
$$u_{L,G1,G2} \frac{\partial T_{L,G1,G2}}{\partial x} = \alpha_{L,G1,G2} \frac{\partial^2 T_{L,G1,G2}}{\partial y^2}$$

Nomenclature:

A, B, C, D, E Constants

H Total Height of Flow Area (m)

$L_{slip1,2}$ Slip Lengths (m)

P Pressure (Pa)

T Temperature

$T_{InletSurf}$ Inlet Surface Temp

c_p Specific Heat Capacity (J/kgK)

$h1, h2$ Height of Gas Layers (m)

$k_{L,1,2}$ Thermal Conductivity (w/mK)

$\alpha_{L,1,2} = \frac{k}{\rho c_p}$

$u_{L,1,2}$ Flow Velocity (m/s)

$\mu_{L,1,2}$ Viscosity (Pas)

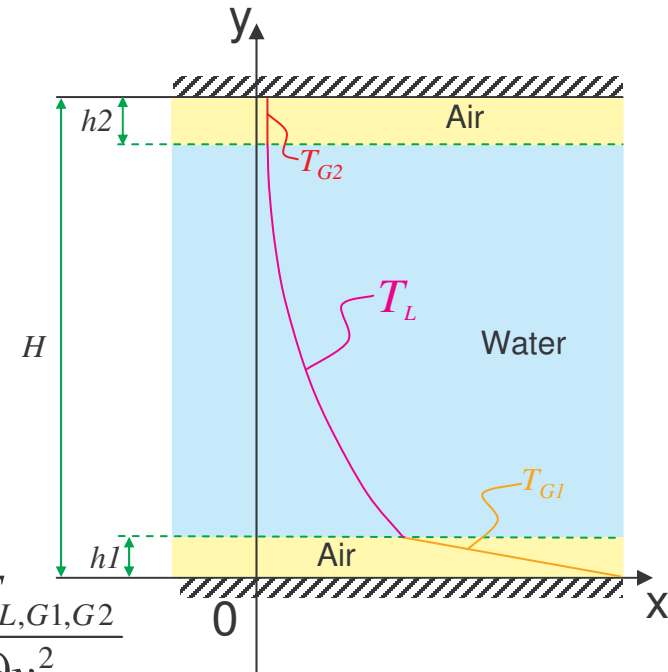
ρ Density (kg/m³)

Subscripts:

$G1, G2$ Property of Gas Layers

L Property of Liquid Layer

m Mean value



Two Wall Temperature Profile Solution

Velocity Profile is of the form: $u(y) = Ay^2 + By + C$

Differential Equation is of the form: $u \frac{\partial T}{\partial x} = \alpha \frac{\partial^2 T}{\partial y^2}$

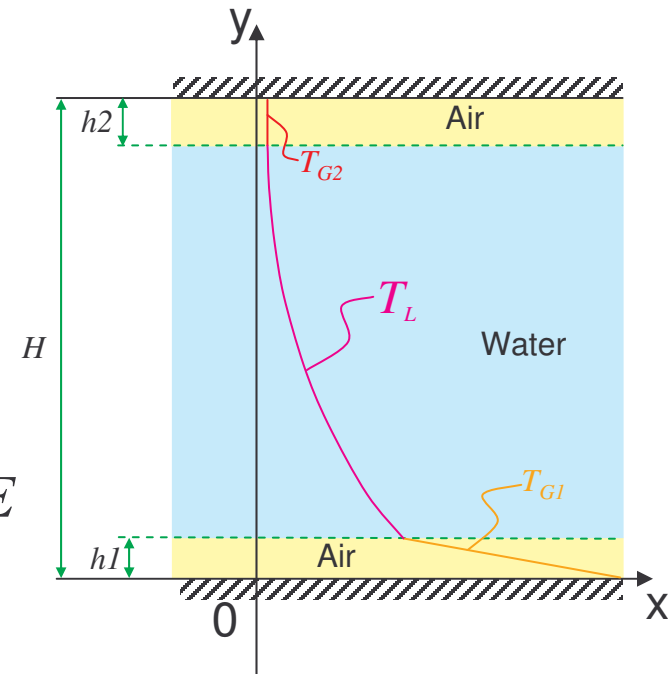
Substituting in the velocity profile and integrating twice wrt y gives:

$$T_{L,G1,G2}(y) = \frac{1}{\alpha} \frac{dT_m}{dx} \left(\frac{Ay^4}{12} + \frac{By^3}{6} + \frac{Cy^2}{2} \right) + Dy + E$$

Note that $\frac{dT_m}{dx}$ is constant for constant heat flux case

The values of A , B and C are known from the velocity profile solution. D and E are integration constants and must be solved for.

This means that six boundary conditions are required as there are three Temperature Profile Equations



Two Wall Temperature Profile Solution

$$T_{L,G1,G2}(y) = \frac{1}{\alpha} \frac{dT_m}{dx} \left(\frac{Ay^4}{12} + \frac{By^3}{6} + \frac{Cy^2}{2} \right) + Dy + E$$

Boundary Conditions:

$$1. \text{ @ } y = 0, -k_{G1} \frac{dT_{G1}}{dy} = \dot{q}$$

New B.C. No.1

$$T_{G1} = \frac{dT_m}{dx} x + T_{InletSurf}$$

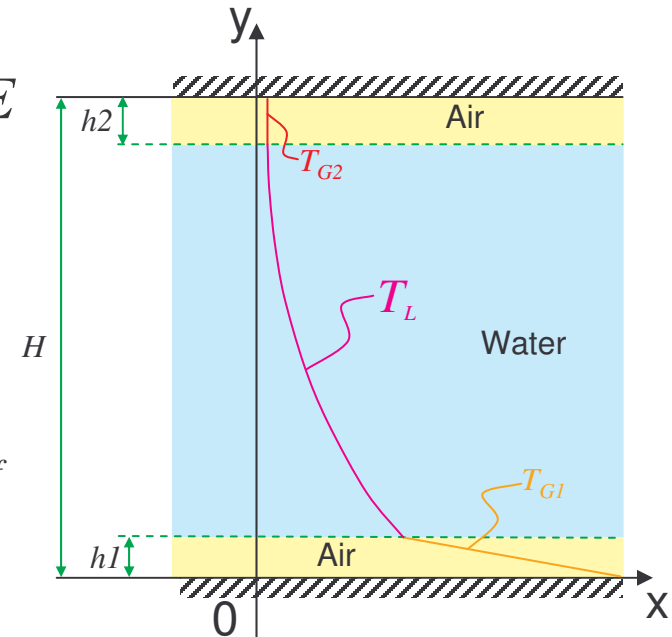
$$2. \text{ @ } y = h1, T_{G1} = T_L$$

$$3. \text{ @ } y = h1, -k_L \frac{dT_L}{dy} = -k_{G1} \frac{dT_{G1}}{dy}$$

$$4. \text{ @ } y = H - h2, T_{G2} = T_L$$

$$5. \text{ @ } y = H - h2, -k_L \frac{dT_L}{dy} = -k_{G2} \frac{dT_{G2}}{dy}$$

$$6. \text{ @ } y = H, -k_{G2} \frac{dT_{G2}}{dy} = 0$$



4 Equations define the D variables, while only 2 define the E variables. Unknowns to be solved for are $D_L, D_{G1}, D_{G2}, E_L, E_{G1}, E_{G2}$. No solution is possible with these boundary conditions.

Since the surface, liquid and gas temperature gradients in the flow direction are constant and equal (Constant heat flux case assumed), a temperature can be assigned to the wall at $y=0$

Two Wall Temperature Profile Solution

